

LC72725KVS

Application Note



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Overview

The LC72725KVS is ICs that implement the signal processing required by the European Broadcasting Union RDS (Radio Data System) standard and by the US NRSC (National Radio System Committee) RBDS (Radio Broadcast Data System) standard. These ICs include band-pass filter, demodulator, and data buffer on chip. RDS data can be read out from this on-chip memory by external clock input in slave operation mode.

Functions

- Bandpass filter : Switched capacitor filter (SCF)
- RDS Demodulation : 57KHz carrier and RDS data clock regeneration, biphase decode, differential decode.
- Buffer : 128 bit (about 100ms) can be restored in the on-chip data buffer.
- Data output : Master or slave output mode can be selected.
- RDS-ID : Detect RDS signal which can be reset by RST signal input.
- Standby control : Crystal oscillator can be stopped.
- Fully adjustment free
- Low Voltage

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The content specified herein is for the purpose of introducing products, if you wish to use any such products, please be sure to refer the datasheet, which can be obtained upon request.

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Specifications

Absolute Maximum Ratings at $T_a = 25^{\circ}\text{C}$, $V_{SSd} = V_{SSa} = 0\text{V}$

Parameter	Symbol	Pin Name	Conditions	Ratings	Unit
Maximum supply voltage	$V_{DD\text{ max}}$	V_{DDd}, V_{DDa}	$V_{DDa} \leq V_{DDd} + 0.3\text{V}$	-0.3 to +6.5	V
Maximum input voltage	$V_{IN1\text{ max}}$	TEST, MODE, RST		-0.3 to +6.5	V
	$V_{IN2\text{ max}}$	XIN, RDCL		-0.3 to $V_{DDd} + 0.3$	V
	$V_{IN3\text{ max}}$	MPXIN, CIN		-0.3 to $V_{DDa} + 0.3$	V
Maximum output voltage	$V_{O1\text{ max}}$	RDS-ID(READY)		-0.3 to +6.5	V
	$V_{O2\text{ max}}$	XOUT, RDDA, RDCL		-0.3 to $V_{DDd} + 0.3$	V
	$V_{O3\text{ max}}$	FLOUT		-0.3 to $V_{DDa} + 0.3$	V
Maximum output current	$I_{O1\text{ max}}$	XOUT, FLOUT, RDDA, RDCL		+3.0	mA
	$I_{O2\text{ max}}$	RDS-ID(READY)		+20.0	mA
Allowable power dissipation	$P_d\text{ max}$		($T_a \leq 85^{\circ}\text{C}$)	100	mW
Operating temperature	T_{opr}		$V_{DD} = 3.0\text{V to } 5.5\text{V}$	-40 to +85	$^{\circ}\text{C}$
Storage temperature	T_{stg}			-40 to +125	$^{\circ}\text{C}$

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

Allowable Operating Ranges at $T_a = -40$ to $+85^{\circ}\text{C}$, $V_{SSd} = V_{SSa} = 0\text{V}$, $V_{DDd} = V_{DDa} = 3.0\text{V to } 5.5\text{V}$

Parameter	Symbol	Pin Name	Conditions	Ratings			unit
				min	typ	max	
Supply voltage	V_{DD}	V_{DDd}, V_{DDa}	$T_a = -40$ to $+85^{\circ}\text{C}$	3.0		5.5	V
Input high-level voltage	V_{IH1}	TEST, MODE, RST		$0.7V_{DDd}$		6.5	V
	V_{IH2}	RDCL		$0.7V_{DDd}$		V_{DDd}	V
Input low-level voltage	V_{IL}	TEST, MODE, RST, RDCL		0		$0.3V_{DDd}$	V
Output voltage	V_{O1}	RDDA, RDCL				V_{DDd}	V
	V_{O2}	RDS-ID(READY)				6.5	V
Input amplitude	V_{IN}	MPXIN	$f = 57 \pm 2\text{kHz}$	1.6		50	mVrms
	V_{XIN}	XIN		400		1500	mVrms
Guaranteed crystal oscillator frequencies	Xtal	XIN, XOUT	$C_L \leq 120\Omega$		4.332		MHz
Crystal oscillator operating range	TXtal	XIN, XOUT	$F_o = 4.332\text{MHz}$			± 100	ppm
RDCL setup time	t_{CS}	RDCL, RDDA		0			μs
RDCL high-level time	t_{CH}	RDCL		0.75			μs
RDCL low-level time	t_{CL}	RDCL		0.75			μs
Data output time	t_{DC}	RDCL, RDDA				0.75	μs
READY output time	t_{RC}	RDCL, READY				0.75	μs
READY low-level time	t_{RL}	READY				107	ms

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Electrical Characteristics at $T_a = -40$ to $+85^\circ\text{C}$, $V_{SSd} = V_{SSa} = 0\text{V}$, $V_{DDd} = V_{DDa} = 3.0\text{V}$ to 5.5V

Parameter	Symbol	Pin Name	Conditions	Ratings			unit
				min	typ	max	
Internal feedback resistance	R_f	XIN			1.0		$\text{M}\Omega$
Hysteresis	VHIS	TEST, MODE, RST, RDCL			$0.1V_{DDd}$		V
Output low-level voltage	V_{OL1}	RDDA, RDCL	$I = 2\text{mA}$			0.4	V
	V_{OL2}	RDS-ID(READY)	$I = 8\text{mA}$			0.4	V
Output high-level voltage	V_{OH}	RDDA, RDCL	$I = -2\text{mA}$	$V_{DDd}-0.54$			V
Input high-level current	I_{IH1}	TEST, MODE, RST, RDCL	$V_I = 6.5\text{V}$			5.0	μA
	I_{IH2}	XIN	$V_I = V_{DDd}$	2.0		11	μA
Input low-level current	I_{IL1}	TEST, MODE, RST, RDCL	$V_I = 0\text{V}$			5.0	μA
	I_{IL2}	XIN	$V_I = 0\text{V}$	2.0		11	μA
Output off leakage current	IOFF	RDS-ID(READY)	$V_O = 6.5\text{V}$			5.0	μA
Current drain	I_{DD}	$V_{DDd}+V_{DDa}$	$V_{DDd}+V_{DDa}$ ($V_{DDd} = V_{DDa} = 3.3\text{V}$)	1.5	2.5	3.5	mA

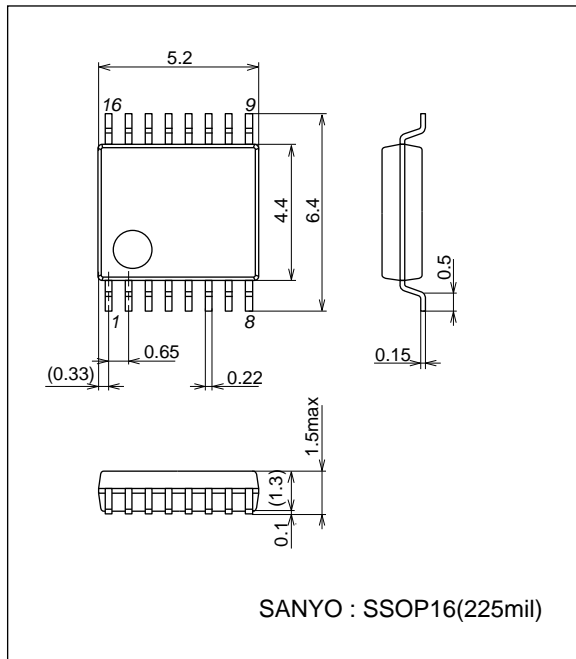
Bandpass Filter Characteristics at $T_a = 25^\circ\text{C}$, $V_{SSd} = V_{SSa} = 0\text{V}$, $V_{DDd} = V_{DDa} = 3.0\text{V}$ to 5.5V

Parameter	Symbol	Pin Name	Conditions	Ratings			unit
				min	typ	max	
Input resistance	R_{mpxin}	MPXIN- V_{SSa}	$f = 57\text{kHz}$		100		$\text{k}\Omega$
	R_{cin}	CIN- V_{SSa}	$f = 57\text{kHz}$		100		$\text{k}\Omega$
Center frequency	f_c	FLOUT		56.5	57.0	57.5	kHz
-3dB band width	BW-3dB	FLOUT		2.5	3.0	3.5	kHz
Gain	Gain	MPXIN-FLOUT	$f = 57\text{kHz}$	28	31	34	dB
Stop band attenuation	Att1	FLOUT	$\Delta f = \pm 7\text{kHz}$	30			dB
	Att2	FLOUT	$f < 45\text{kHz}$, $f > 70\text{kHz}$	40			dB
	Att3	FLOUT	$f < 20\text{kHz}$	50			dB
Reference voltage output	V_{ref}	V_{ref}	$V_{DDa} = 3\text{V}$		1.5		V

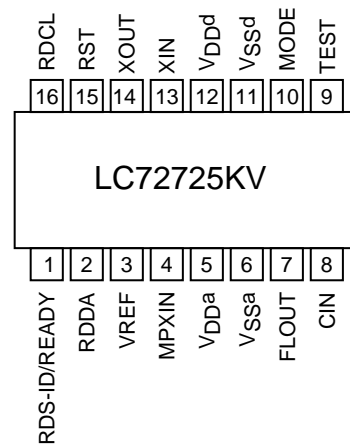
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Package Dimensions

unit : mm (typ)
3178B

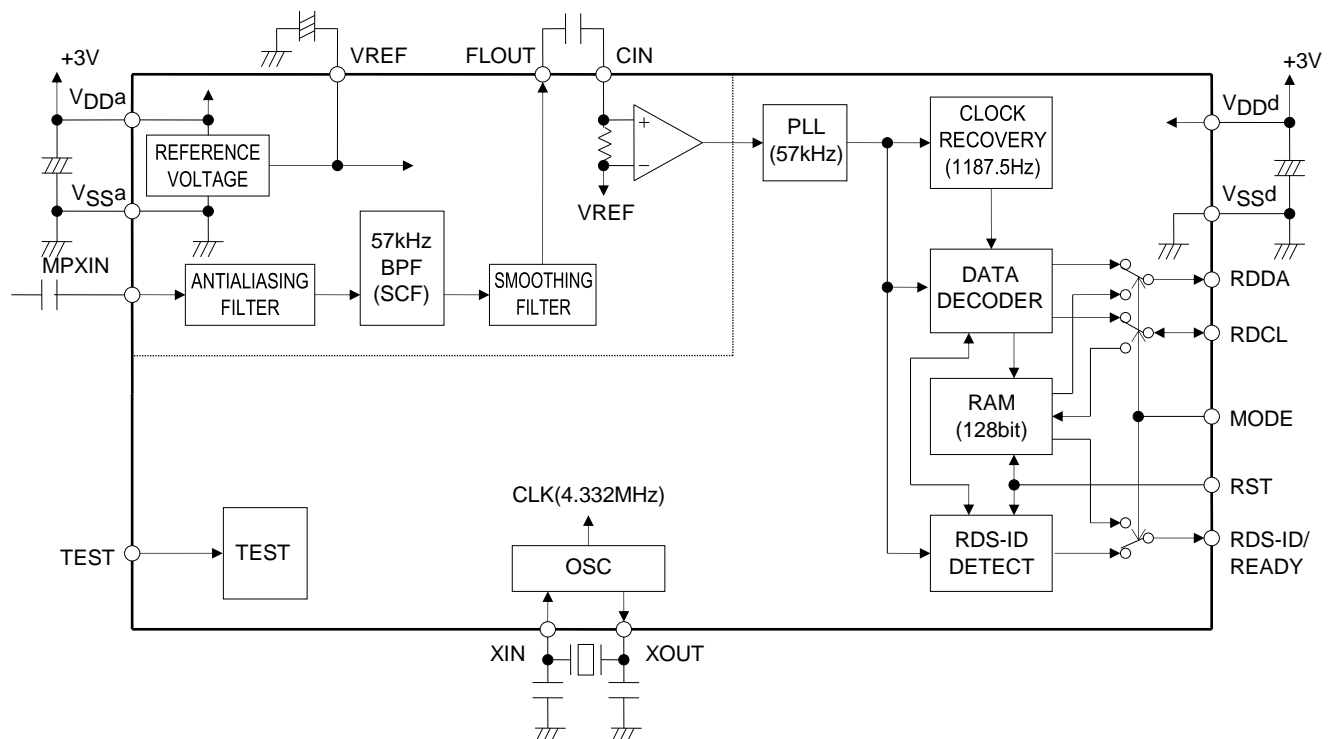


Pin Assignment



Top view

Block Diagram



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Pin Descriptions

Pin No.	Pin Name	I/O	Function	Pin Circuit
3	VREF	Output	Reference voltage output ($V_{DDa}/2$)	
4	MPXIN	Input	Baseband (multiplexed) signal input	
7	FLOUT	Output	Subcarrier output (filter output)	
8	CIN	Input	Subcarrier input (comparator input)	
5	V_{DDa}	-	Analog system power supply (+3V)	-
6	V_{SSa}	-	Analog system ground	-
14	XOUT	Output	Crystal oscillator output (4.332MHz)	
13	XIN	Input	Crystal oscillator input (external reference signal input)	
9	TEST		Test input	
10	MODE		Read out mode (0:master, 1:slave)	
15	RST		RDS-ID/RAM reset (active high)	
2	RDDA	Output	RDS data output	
16	RDCL	I/O	RDS clock output (master mode) / RDS read out clock input (slave mode)	
1	RDS-ID/ READY	Output	RDS reliability data output (High: data with high RDS reliability Low: data with low RDS reliability) READY output (active high)	
12	V_{DDd}	-	Digital system power supply (+3V)	-
11	V_{SSd}	-	Digital system ground	-

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Input/Output Data Format

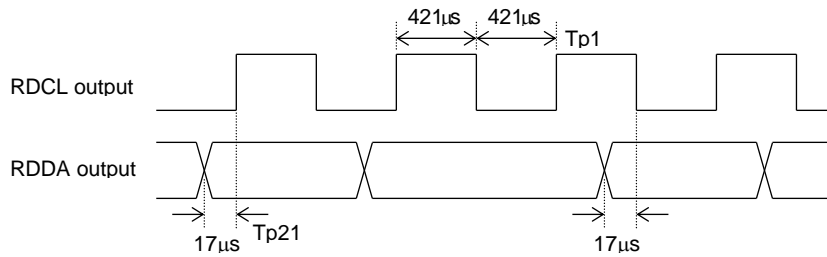
TEST	MODE	Circuit Operation Mode	RDCL Pin	RDS-ID/READY Pin
0	0	Master read out mode	Clock output	RDS-ID output
0	1	Slave read out mode	Clock input	READY output
1	0	Standby mode (crystal oscillator stopped)	-	-
1	1	IC test mode which is not available to user applications.	-	-

	RST Pin
RST = 0	Normal operation
RST = 1	RDS-ID • demodulation circuit clear + READY • memory clear (when slave mode)

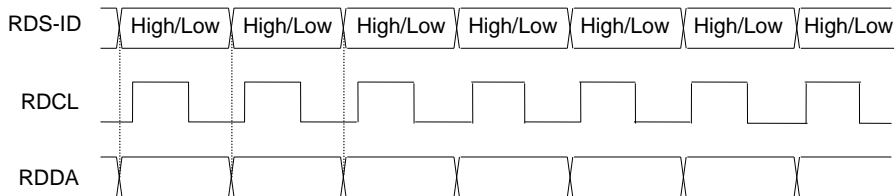
	RDS-ID/READY Pin
Master mode	RDS-ID output (Active-high)
Slave mode	READY output (Active-high)

Note: RDS-ID(READY) pin is an n-channel open-drain output, and requires an external pull-up resistor to output data.

RDCL/RDDA Output Timing in Master Mode

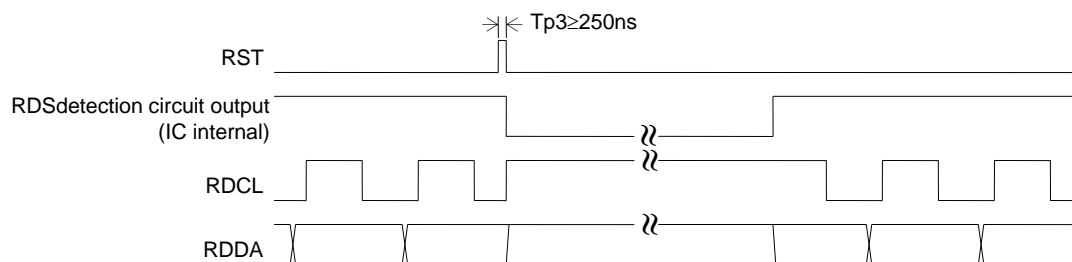


RDS-ID Output Timing



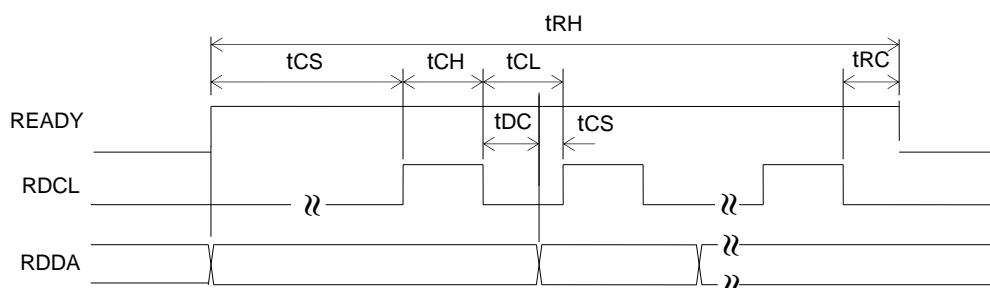
Note: RDS-ID is High: data with high RDS reliability, Low: data with low RDS reliability

RST Operation in Master Mode



Note: RDCL and RDDA outputs keep high level after input of RST until RDS detection circuit output is detected.

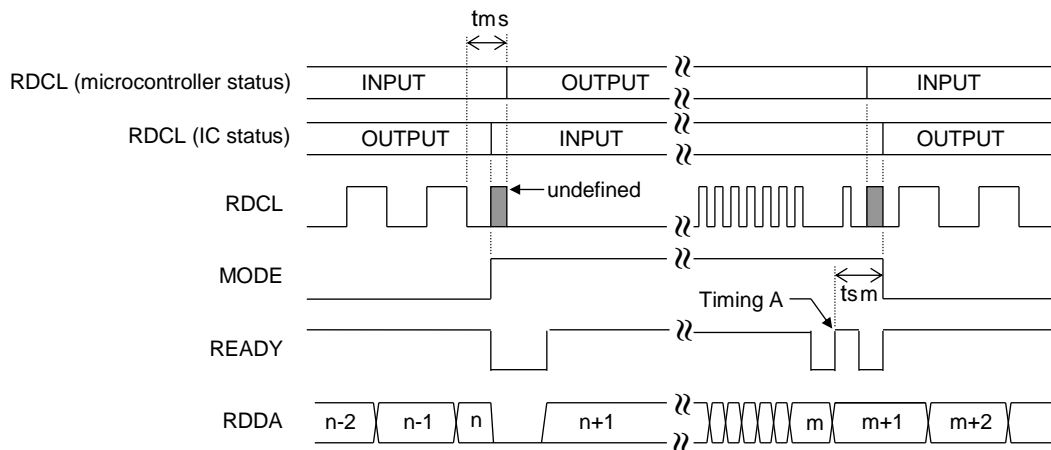
RDCL Operation in Slave Mode



Parameter	Symbol	Pin Name	Conditions	Ratings			unit
				min	typ	max	
RDCL setup time	tCS	RDCL,RDDA		0			μs
RDCL high-level time	tCH	RDCL		0.75			μs
RDCL low-level time	tCL	RDCL		0.75			μs
Data output time	tDC	RDCL,RDDA				0.75	μs
READY output time	tRC	RDCL,READY				0.75	μs
READY high-level time	tRH	READY				107	ms

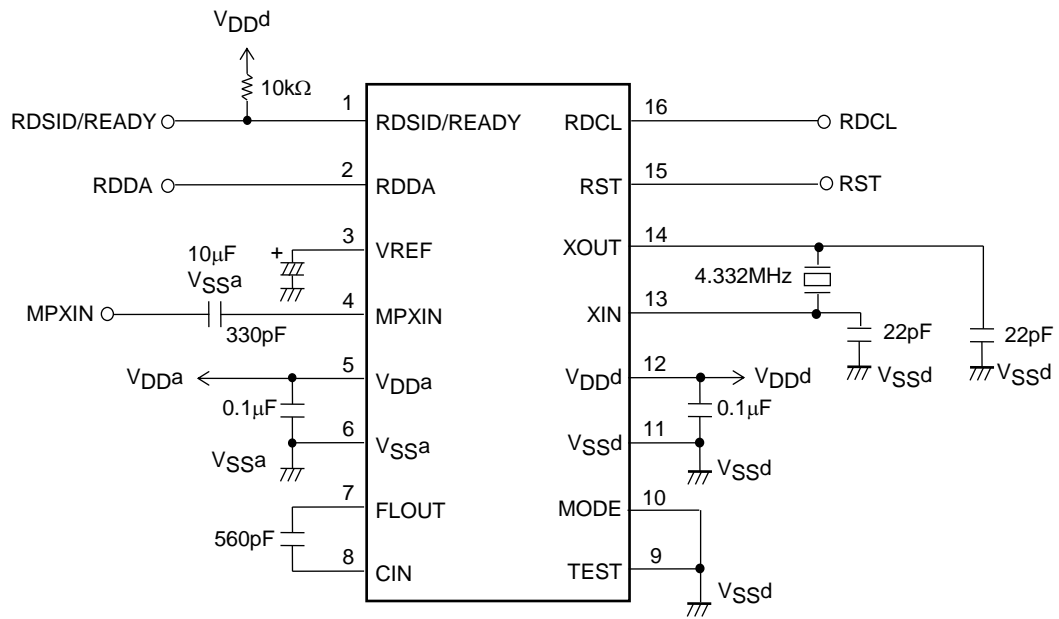
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- Notes: 1. RDCL input must be started after READY signal goes high. When READY signal is low, RDCL must be low level.
2. READY status must be checked after t_{RC} time from RDCL is set low. If the READY status is high, then next read cycle can be continued. If the READY status is low, next RDCL clock input must be stopped.
3. If the above condition is satisfied, RDS data (RDDA) can be read out at both rising and falling edge of RDCL.
4. READY signal goes low after the last data is read out from on-chip memory. If one RDS data is stored in the memory, READY signal goes high again.
5. When the reception channel is changed, a memory and READY reset must be applied using RST input. If a reset is not applied, reception data from the previous channel may remain in memory. If RST input is applied, reception data is not stored in memory until the first RDS-ID is detected, and READY output goes high after the first RDS-ID is detected. After the first RDS-ID is detected, reception data is stored even if RDS-ID is not detected.
6. The readout mode may be switched between master and slave modes during readout.
- Applications must observe the following points to assure data continuity during this operation.
- 1) Data acquisition timing in master mode
Data must be read on the falling edge of RDCL
 - 2) Timing of the switch from master mode to slave mode
After the RDCL output goes low and the RDDA data has been acquired, the application must set MODE high immediately.
Then, the microcontroller starts output by setting the RDCL signal low.
The microcontroller RDCL output must start within 840 μ s (t_{ms}) after RDCL went low.
In this case, if the last data read in master mode was data item n, then data starting with item n+1 will be written to memory.
 - 3) Timing of the switch from slave mode to master mode
After all data has been read from memory and READY has gone high, the application must then wait until READY goes low once again the next time (timing A in the figure), immediately read out one bit of data and input the RDCL clock.
Then, at the point READY goes high, the microcontroller must terminate RDCL output and then set MODE low.
The application must switch MODE to low within 840 μ s (t_{ms}) after READY goes low (timing A in the figure).



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Sample Application Connection Circuit (for master mode operation)



Note: If the RST pin is unused, it must be connected to the ground.

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Evaluation board
100mm x 100mm

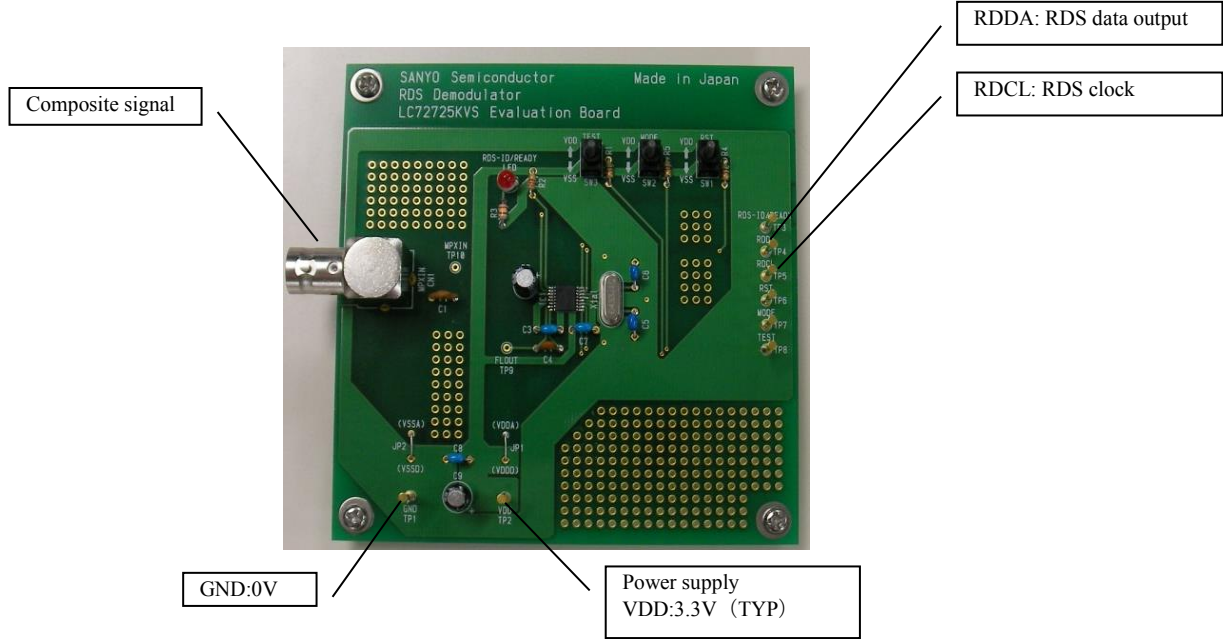
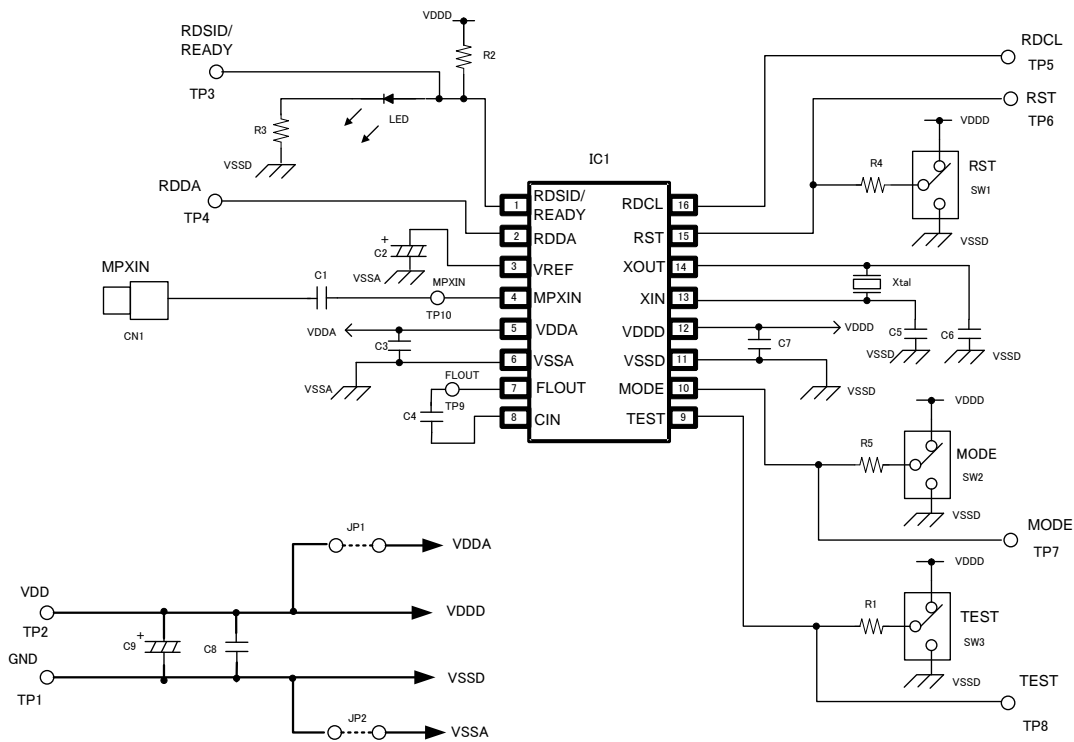


Fig.1 The schematic for LC72725KVS evaluation board

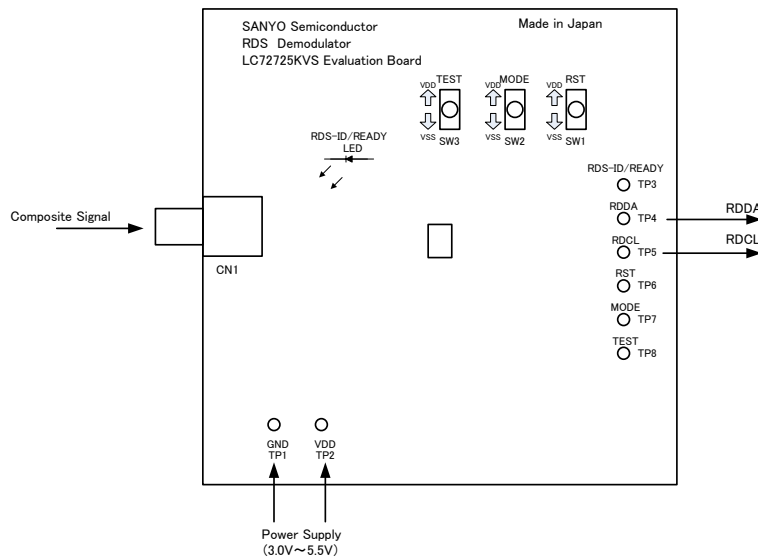


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Bill of Materials for LC72725KVS Evaluation Board

signator	Quantity	Description	Value	Tolerance	Package (inch)	Manufacturer	Manufacturer Part Number	Substitution Allowed	Lead Free
IC1	1	RDS Demodulator			SSOP16 (225mil)	ON SEMI	LC72725KVS	No	YES
Xtal	1	Crystal Resonator	4.332MHz (CL=12pF)	±100ppm		DAISHINKU	AT-49	YES	YES
CN1	1	BNC connector				HIROSE ELECTRIC	BNC-LR-PC-3(40)	YES	YES
C1	1	DC coupling	330pF,50V	±5%		MURATA Supertech Electronic	RPE2C1H331J2 RD15N331J1HL2L	YES	YES
C2	1	Decoupling	10μF,16V	±20%		SUN Electronic Industries Corp.	16ME10HC	YES	YES
C3	1	Bypass Capacitor	0.1μF,50V	+80/-20%		MURATA	RPEF11H104Z2K1	YES	YES
C4	1	DC coupling	560pF,50V	±5%		MURATA	RPE2C1H561J2	YES	YES
C5	1	External capacitor for oscillator	22pF,50V	±5%		MURATA Supertech Electronic	RPE2C1H220J2 RD15N220J1HH5L	YES	YES
C6	1	External capacitor for oscillator	22pF,50V	±5%		MURATA Supertech Electronic	RPE2C1H220J2 RD15N220J1HH5L	YES	YES
C7	1	Bypass Capacitor	0.1μF,50V	+80/-20%		MURATA	RPEF11H104Z2K1	YES	YES
C8	1	Bypass Capacitor	0.1μF,50V	+80/-20%		MURATA	RPEF11H104Z2K1	YES	YES
C9	1	Decoupling	100μF,16V	±20%		SUN Electronic Industries Corp.	16ME100HC	YES	YES
R1	1	Pull-up /Pull down Resistor	5.6KΩ, 0.166W	±5%		AKAHANE Electronics Ind.Corp	RD16**562J	YES	YES
R2	1	Pull-up Resistor	1.2KΩ, 0.166W	±5%		AKAHANE Electronics Ind.Corp	RD16**122J	YES	YES
R3	1	for current limiting	240Ω,0.166W	±5%		AKAHANE Electronics Ind.Corp	RD16**241J	YES	YES
R4	1	Pull-up /Pull down Resistor	5.6KΩ, 0.166W	±5%		AKAHANE Electronics Ind.Corp	RD16**562J	YES	YES
R5	1	Pull-up /Pull down Resistor	5.6KΩ, 0.166W	±5%		AKAHANE Electronics Ind.Corp	RD16**562J	YES	YES
LED	1	Indicator for RDS-ID				Opto Supply Limited	OSRR3133A	YES	YES
SW1-SW4	4	Switch				NIHON KAIHEIKI	G-12AP	YES	YES
TP1-TP8	8	Test Pin				Mac Eight	ST-1-3	YES	YES

Fig.2 Illustration of LC72725KVS evaluation board



How to use:

1. Connect the power supply to VDD (TP2) and GND (TP1).
(+3.3V to +5.5V)
2. Input composite signals to the BNC connector (CN1).
3. Toggle SW1 (RST) and SW2 (MODE) and SW3 (TEST) to "VSS" side.
4. If the LC72725KVS detects RDS signal in composite signal, RDS-ID output level turns "H". And the LED lights up.
5. Connect RDCL and RDDA with RDS encoder (as shown in Fig.3) to measure error rate.

Appendix

Description of SW1 and SW2 and SW3:

(1)SW3 (TEST)

SW3=VDD: Standby mode is on when MODE (SW2) is switched to "VSS" side (Crystal circuit is stopped.).

SW3=VDD: LSI test mode is on when MODE (SW2) is switched to "VDD" side.

(Basically, customer cannot switch SW2 to VDD side.)

SW3=VSS: Once RDS signal is received, the signal is output from RDCL and RDDA, respectively.

(2)SW2 (MODE)

SW2=VDD: Slave mode is on when TEST is switched to "VSS" side. RDS clock must be input to RDCL externally. RDS-ID/READY is set to READY output port.

SW2=VSS: Once the RDS signal is received, the signal is output from RDCL and RDDA, respectively.

(3)SW1 (RST)

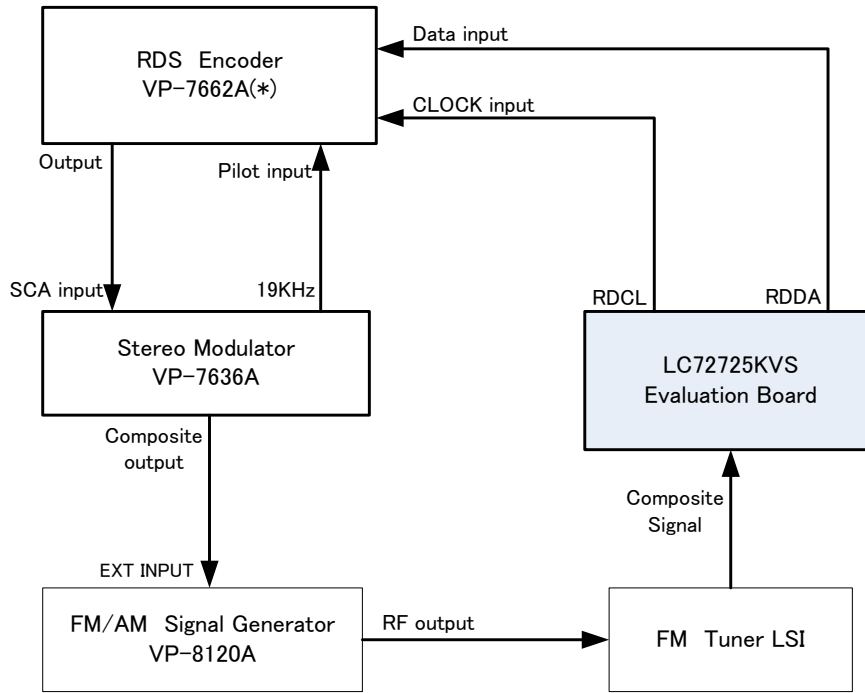
SW1=VDD: RDS-ID and internal buffer are reset. Once the RDS signal is received, the signal is output from RDCL and RDDA.

—————> The internal circuit is reset.

SW1=VSS: Once the RDS signal is received, the signal is output from RDCL and RDDA.

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Fig.3 Bit error rate measurement

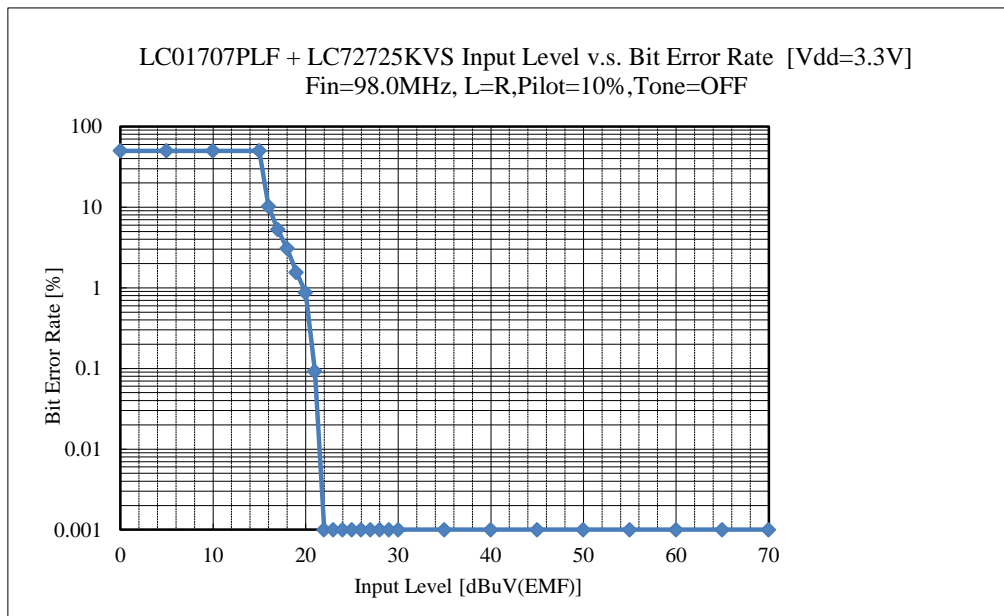


(*)RDS encoder(VP-7662A) is no longer in production. An equivalent model is MEGURO MSG-2174.

Reference data

FM Tuner LSI used LC01707PLF.

The bit error rate of LC72725KVS is as shown below.



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